

InGaAs area image sensors

**G17242-0808T G17243-0808T**

Wide spectral response range (0.9 to 2.55 μm), Near infrared two-dimensional image sensor (320 × 256 pixels)

G17242/G17243-0808T are InGaAs area image sensors designed for near infrared hyperspectral imaging. InGaAs chips with different cutoff wavelengths are arranged in parallel with high accuracy to achieve high S/N over a wide spectral response range. It uses a hybrid structure consisting of a CMOS readout circuit (ROIC: readout integrated circuit) and back-illuminated InGaAs photodiodes. Each pixel is made up of an InGaAs photodiode and a ROIC electrically connected by indium bump. The timing generator in the ROIC provides an analog video output which is obtained by just supplying digital inputs.

■ Features

- Dynamic range: 3500
- 4-port analog output
- Frame rate: 503 frames/s max.
(All-line readout mode, integration time=1.98 ms,
during IWR operation)
- Low dark current
- Operation of integrate while readout function and
integrate then readout function can be done.
- Multi-line readout function
- Simple operation (built-in timing generator)
- Three-stage TE-cooled type

■ Applications

- Hyperspectral imaging
(food sorting, metal exploration, etc.)

■ Selection guide

Type no.	Number of InGaAs chips	Area	Spectral response range Tchip=-20 °C (μm)
G17242-0808T	2	1.7 μm area	0.9 to 1.65
		2.2 μm area	1.3 to 2.15
G17243-0808T	3	1.7 μm area	0.9 to 1.65
		2.2 μm area	1.3 to 2.15
		2.6 μm area	1.7 to 2.55

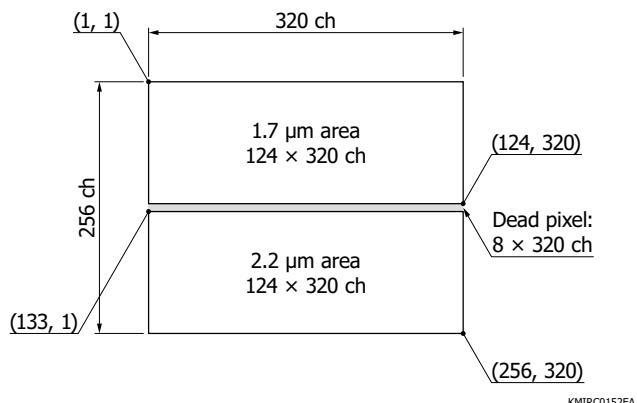
Structure

Parameter	G17242-0808T	G17243-0808T	Unit
Image size	6.40 × 2.48 (1.7 μm area) 6.40 × 2.48 (2.2 μm area)	6.40 × 1.60 (1.7 μm area) 6.40 × 1.60 (2.2 μm area) 6.40 × 1.60 (2.6 μm area)	mm
Pixel size	20 × 20		μm
Pixel pitch	20		μm
Number of total pixels*1	320 × 256		Pixel
Number of effective pixels	320 × 248	320 × 240	Pixel
Number of output ports	4		Port
Fill factor	100		%
Package	28-pin metal		-
Window material	AR-coated sapphire glass		-
Cooling	Three-stage TE-cooled		-

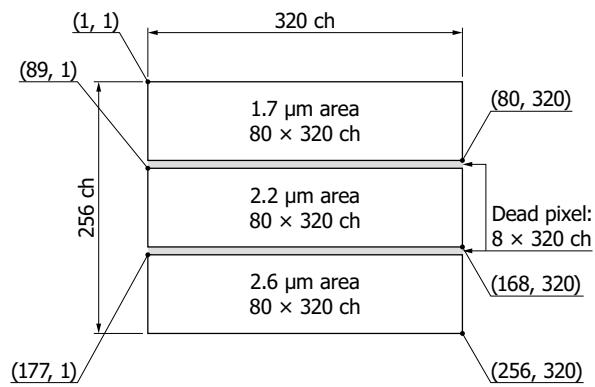
*1: Including dead pixels

Configuration of photosensitive area

G17242-0808T



G17243-0808T

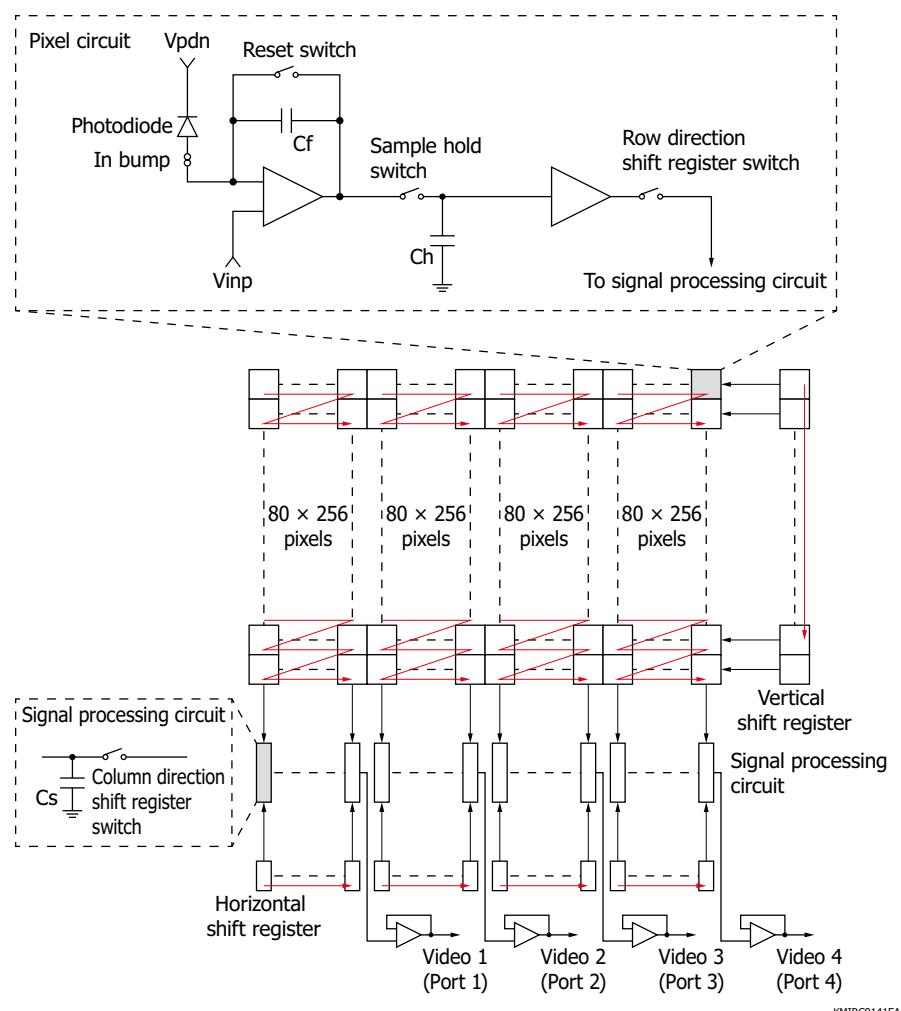


Block diagram

The series of operations of the readout circuit are described below.

G17242/G17243-0808T can support both integrate while readout mode (IWR) and integrate then readout mode (ITR) by switching the input timing.

- 1) Turn on the reset switch to reset.
- 2) After turning off the reset switch, turn on the sample hold switch to start integration. Pixel optical signal information is integrated in the capacitance Cf as a signal voltage.
- 3) Turn off the sample hold switch to end the integration. The pixel signal voltage is held in capacitance Ch.
- 4) Turn on the reset switch to reset the pixel signal voltage integrated in the capacitance Cf.
- 5) The vertical shift register turns on the row direction shift register switch in the first row, and the signal voltage is transferred to the capacitance Cs.
- 6) The horizontal shift register turns on the column direction shift register switch in the first row and first column of each port.
- 7) The next horizontal shift register of each port, and the output signals (Video1 to 4) are read out sequentially.
- 8) Repeat steps 5) to 7) for each row. (When doing the IWR operation, turn off the reset switch and start integrating.)
- 9) To perform the next integration, return to step 2.



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Absolute maximum ratings

Parameter	Symbol	Condition	Value	Unit
Supply voltage (5 V)	Vdd1, Vb1, Vinp, Vpdn	Ta=25 °C	-0.3 to +6.0	V
Supply voltage (3.3 V)	Vdd2, Vrst	Ta=25 °C	-0.3 to +4.2	V
Input signal voltage	Vi	Ta=25 °C	-0.3 to +4.2	V
Operating temperature*2 *3	Topr		-30 to +60	°C
Storage temperature*3	Tstg		-40 to +70	°C
Thermistor power dissipation	Pd_th		400	mW
TE-cooler allowable current*4 *5	ITE max.		3.5	A
TE-cooler allowable voltage*4 *6	VTE max.		7.8	V
Maximum temperature of heat dissipation side*7	-		70	°C

*2: Chip temperature

*3: No dew condensation

When there is a temperature difference between a product and the surrounding area in high humidity environments, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

*4: Th=25 °C, Th is the temperature on the heat dissipation side of the built-in TE-cooler.

*5: The current value that provides the maximum temperature difference between the heat absorption side and the heat dissipation side of the TE-cooler in a completely insulated state. We recommend using at 80% of the maximum current value due to the load on the TE-cooler and stability of temperature.

*6: The voltage required between the TE-cooler terminals to allow maximum current to flow.

*7: If the temperature on the heat dissipation side exceeds this temperature, the TE-cooler may degrade.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

■ Electrical and optical characteristics

(Ta=25 °C, Tchip=-20 °C, Vdd1=5.0 V, Vdd2=3.3 V, Vpdn=3.18 V, Vinp=3.1 V, Vrst=1.7 V, fop=50 MHz)

G17242-0808T

Parameter	Symbol	G17242-0808T			Unit
		Min.	Typ.	Max.	
Spectral response range	λ	-	0.9 to 1.65	-	μm
			1.3 to 2.15		
Peak sensitivity wavelength	λ_p	-	1.55	-	μm
			1.95		
Photosensitivity	S	0.7	0.8	-	A/W
		0.85	1.0		
Conversion efficiency	CE	-	2.0	-	$\mu\text{V/e}^-$
Saturation charge	Csat	0.8	1.05	-	Me^-
Saturation output voltage	Vsat	1.6	2.1	-	V
Photoresponse nonuniformity*8	PRNU	-	± 10	± 20	%
			± 10	± 30	
Dark current	ID	-	0.01	0.1	pA
			3.0	30	
Dark output nonuniformity*9	DSNU	-	± 0.1	± 0.12	V
			± 0.1	± 0.6	
Readout noise*10	Nread	-	600	1400	$\mu\text{V rms}$
		-	300	700	e^-
Dynamic range	Drange	1500	3500	-	-
Defective pixels*11	-	-	-	0.37	%
				1.0	

*8: Measured at 50% saturation after subtracting the dark output, excluding first and last pixels on each row

Integration time=0.5 ms

*9: Integration time=0.5 ms

*10: Integration time=8.76 μs

*11: Pixels whose saturation output voltage, photoresponse nonuniformity, dark current, dark output nonuniformity, or readout noise is outside the specifications

G17242-0808T

Area	Maximum number of defective pixels	Percentage of maximum defective pixels
1.7 μm area	146 pixel	0.37%
2.2 μm area	396 pixel	1%

G17243-0808T

Parameter	Symbol	G17243-0808T			Unit
		Min.	Typ.	Max.	
Spectral response range	λ	-	0.9 to 1.65	-	μm
			1.3 to 2.15		
			1.7 to 2.55		
Peak sensitivity wavelength	λ_p	-	1.55	-	μm
			1.95		
			2.25		
Photosensitivity	S	0.7 0.85 0.8	0.8	-	A/W
			1.0		
			1.0		
Conversion efficiency	CE	-	2.0	-	$\mu\text{V/e}^-$
Saturation charge	Csat	0.8	1.05	-	Me^-
Saturation output voltage	Vsat	1.6	2.1	-	V
Photoresponse nonuniformity ^{*12}	PRNU	-	± 10	± 20	%
			± 10	± 30	
			± 10	± 30	
Dark current	ID	-	0.01	0.1	pA
			3.0	30	
			30	300	
Dark output nonuniformity ^{*13}	DSNU	-	± 0.1	± 0.12	V
			± 0.1	± 0.6	
			± 0.1	± 0.6	
Readout noise ^{*14}	Nread	-	600	1400	$\mu\text{V rms}$
			300	700	e^-
Dynamic range	Drange	1500	3500	-	-
Defective pixels ^{*15}	-	-	-	0.37	%
				1.0	
				1.0	

*12: Measured at 50% saturation after subtracting the dark output, excluding first and last pixels on each row
 Integration time=0.5 ms

*13: Integration time=0.5 ms

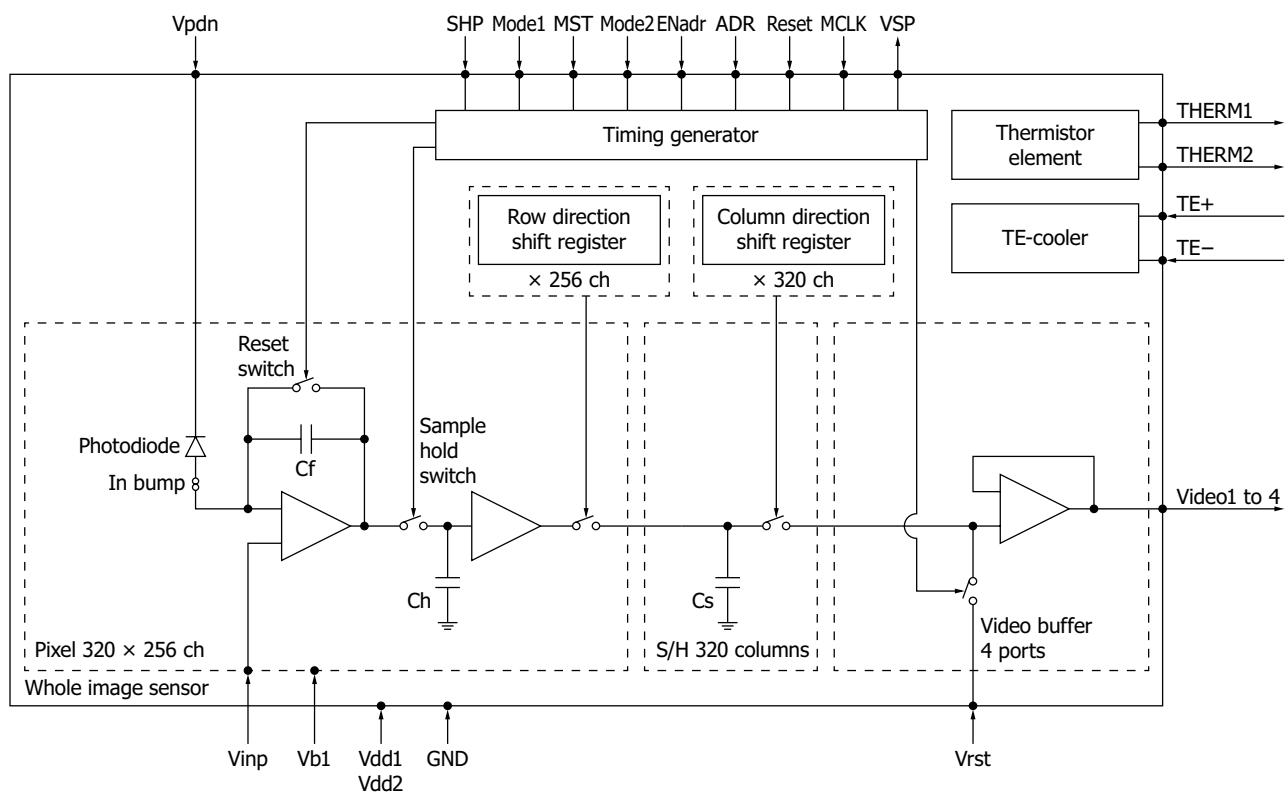
*14: Integration time=8.76 μs

*15: Pixels whose saturation output voltage, photoresponse nonuniformity, dark current, dark output nonuniformity, or readout noise is outside the specifications

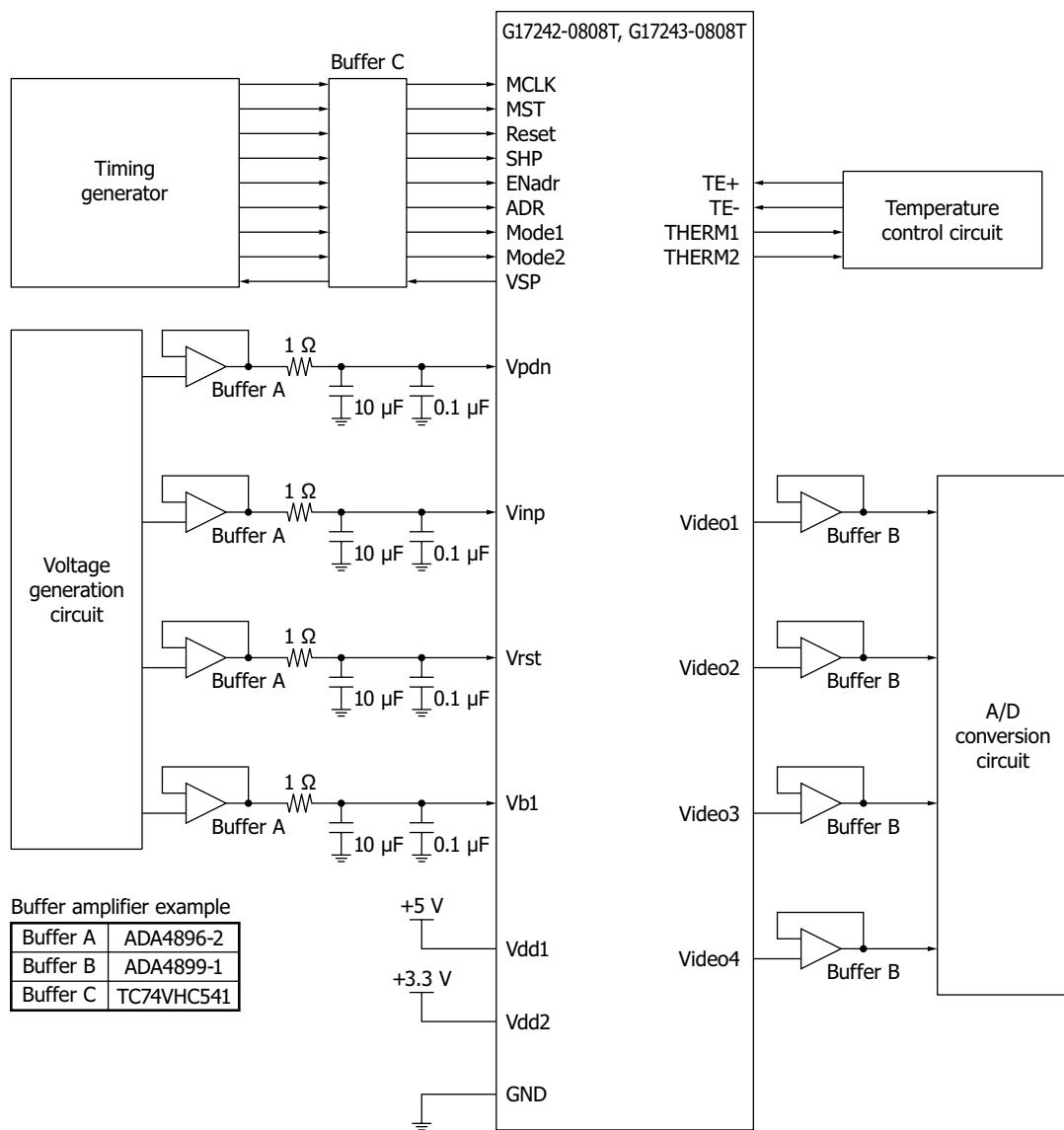
■ G17243-0808T

Area	Maximum number of defective pixels	Percentage of maximum defective pixels
1.7 μm area	94 pixel	0.37%
2.2 μm area	256 pixel	1%
2.6 μm area	256 pixel	1%

■ Equivalent circuit



Connection example



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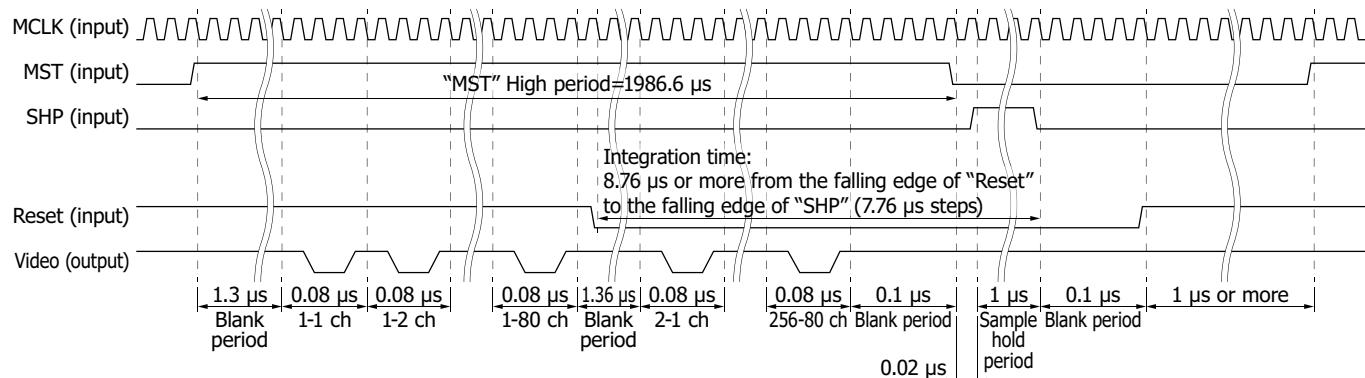
Timing chart

G17242/G17243-0808T can support both integrate while readout mode (IWR) and integrate then readout mode (ITR) by switching the input timing. For details, see the timing chart.

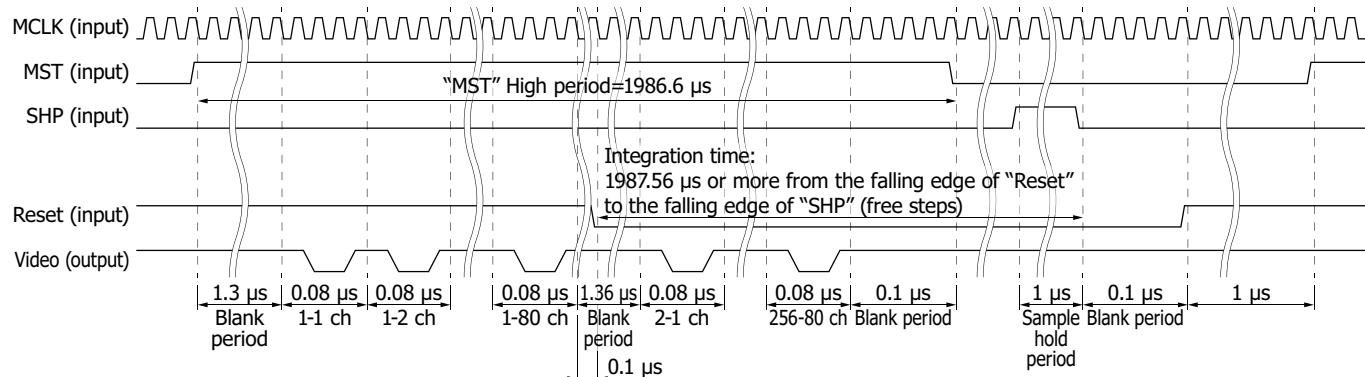
All-line readout mode_IWR mode

IWR all-line readout mode [MCLK frequency: 50 MHz, falling period, "Mode2" setting: 3.3 V (High)]

Case (1) Integration time<readout period (when integration time is 8.76 μ s to 1979.8 μ s)



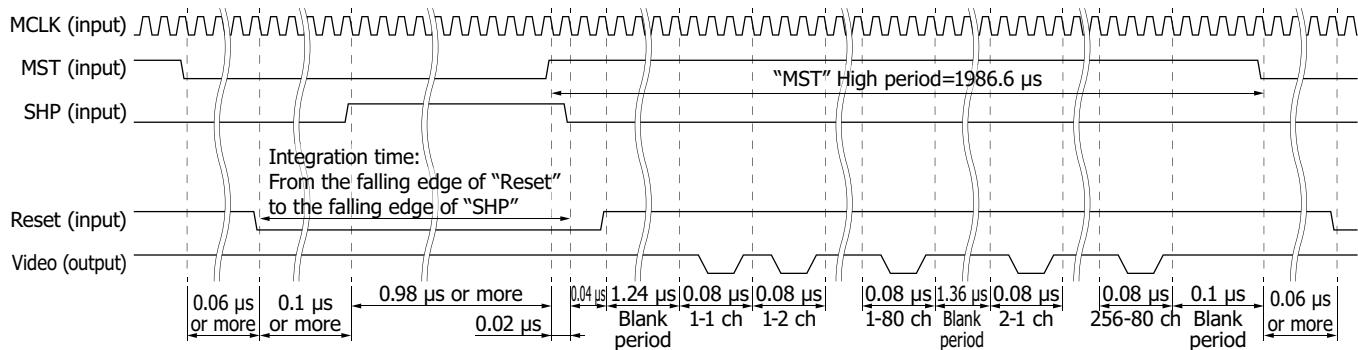
Case (2) Integration time>readout period (when integration time is 1979.8 μ s or more)



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All-line readout mode_ITR mode

ITR all-line readout mode [MCLK frequency: 50 MHz, falling period/cycle, "Mode2" setting: 3.3 V (High)]

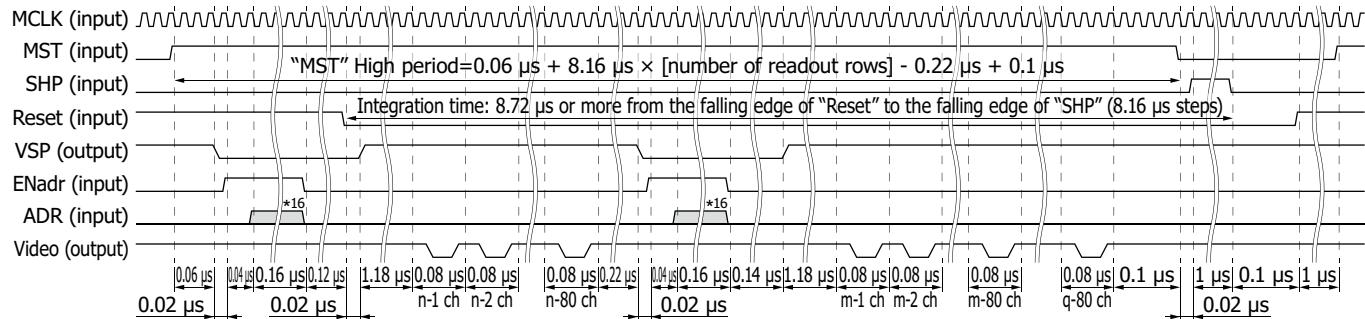


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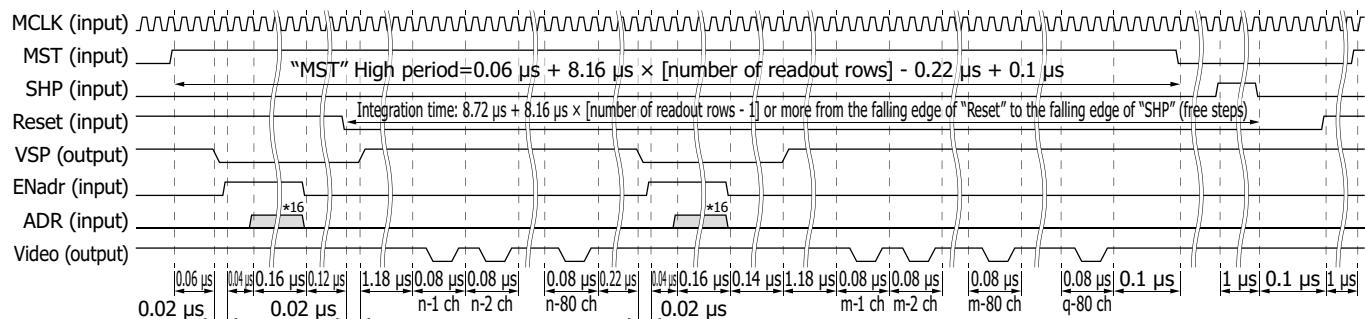
■ Multi-line readout mode_IWR mode

IWR multi-line readout mode [MCLK frequency: 50 MHz, falling periodcycle, "Mode2" setting: 0 V (Low)]

Case (1) Integration time<readout period (when integration time is 8.72 μ s to 8.72 μ s + 8.16 μ s × [number of readout rows - 1])



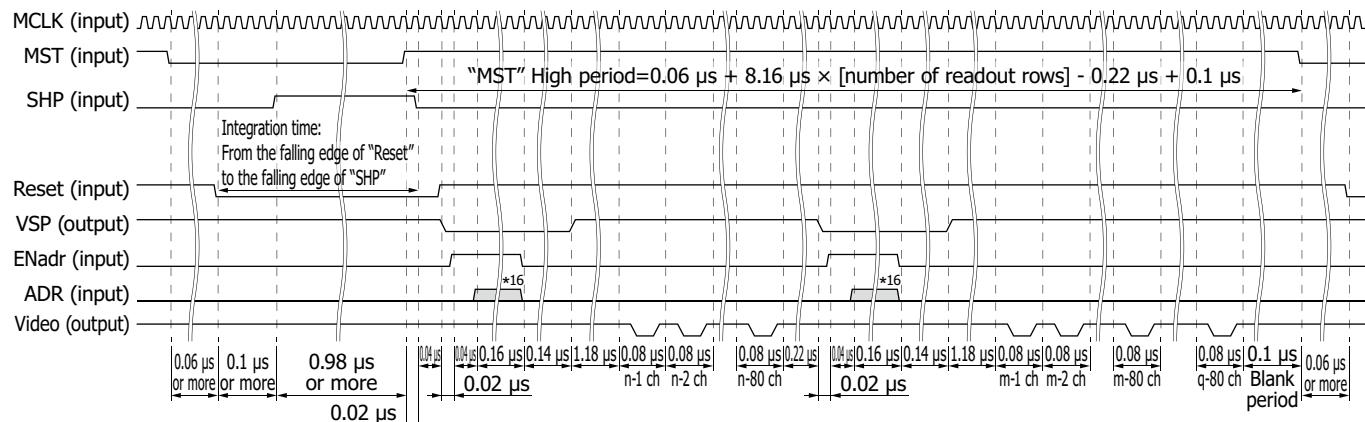
Case (2) Integration time>readout period (when integration time is 8.72 μ s + 8.16 μ s × [number of readout rows - 1])



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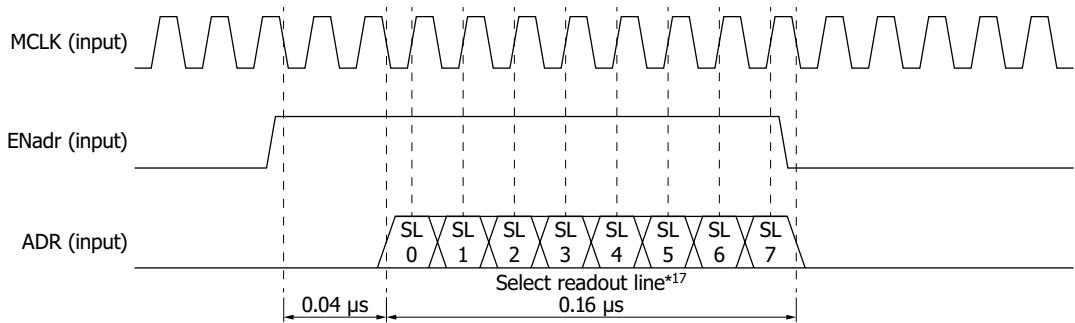
■ Multi-line readout mode_ITR mode

ITR multi-line readout mode [MCLK frequency: 50 MHz, falling period, "Mode2" setting: 0 V (Low)]



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*16: ADR signal setting of multi-line readout mode



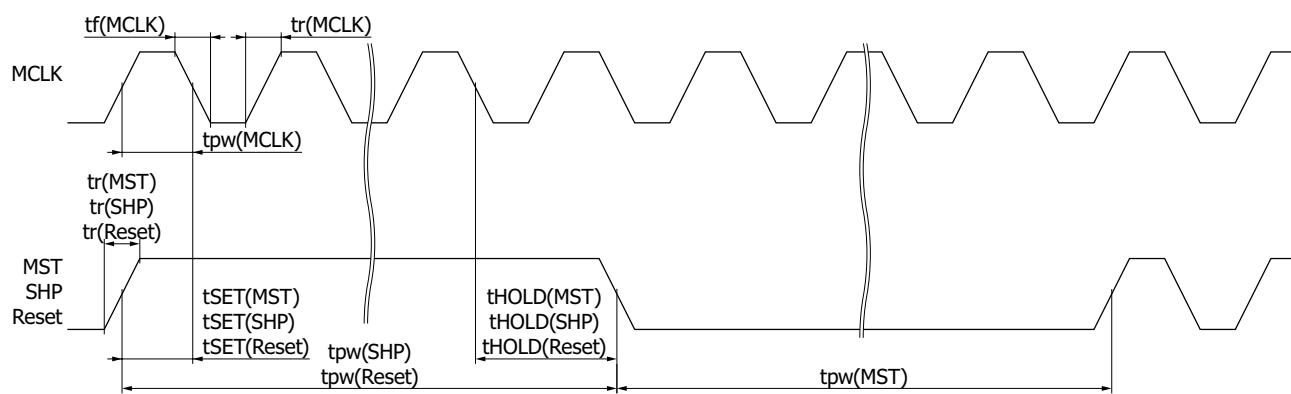
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*17: ADR signal setting example

Select Line Row-ch	SL Address Decimal	SL Address Binary	SL0	SL1	SL2	SL3	SL4	SL5	SL6	SL7
1	0	00000000	0	0	0	0	0	0	0	0
11	10	00001010	0	1	0	1	0	0	0	0
129	128	10000000	0	0	0	0	0	0	0	1
200	199	11000111	1	1	1	0	0	0	1	1
234	233	11101001	1	0	0	1	0	1	1	1
256	255	11111111	1	1	1	1	1	1	1	1

■ Timing specifications (MCLK, MST, SHP, Reset)

Timing specifications of external input signals (MCLK, MST, SHP, Reset) are shown below.



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■ Specifications of external input signals (MCLK, MST, SHP, Reset)

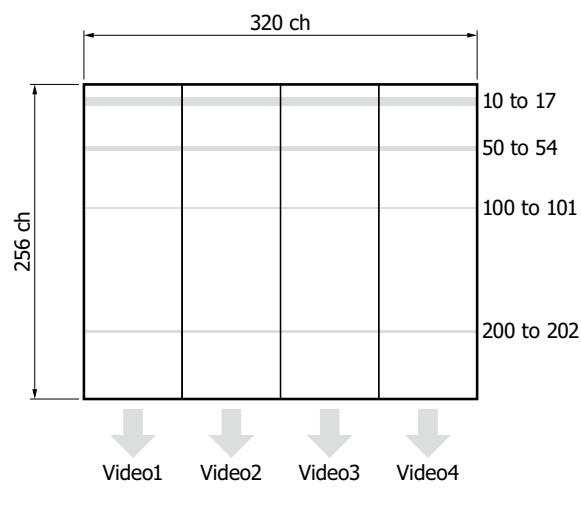
Parameter	Symbol	Min.	Typ.	Max.	Unit
Clock frequency	fop	-	-	50	MHz
Clock pulse width	tpw(MCLK)	10	-	-	ns
Clock pulse rise/fall times	tr(MCLK), tf(MCLK)	-	3	4	ns
Master start pulse width	tpw(MST)	40	-	-	ns
Sample hold pulse width	tpw(SHP)	1000	-	-	ns
Reset pulse width	tpw(Reset)	1000	-	-	ns
Master start pulse rise/fall times Sample hold pulse rise/fall times Reset pulse rise/fall times	tr(MST), tf(MST), tr(SHP), tf(SHP), tr(Reset), tf(Reset)	-	3	4	ns
Setup time	tSET(MST), tSET(SHP), tSET(Reset)	5	-	-	ns
Hold time	tHOLD(MST), tHOLD(SHP), tHOLD(Reset)	5	-	-	ns

■ Multi-line readout mode

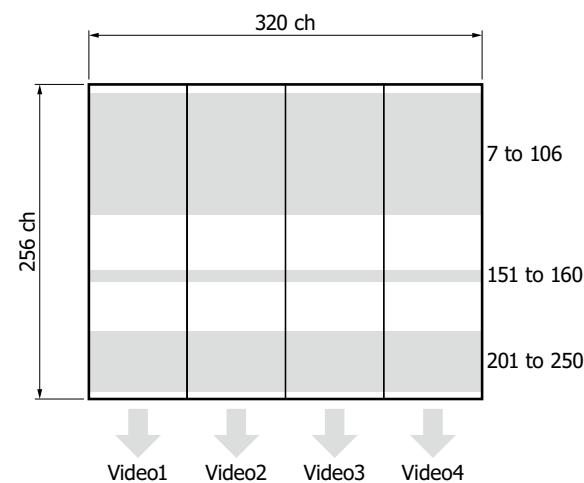
G17242/G17243-0808T can be set to multi-line readout mode in addition to normal readout mode (all line readout mode). By setting to multi-line readout mode, it is possible to freely read any row (multi-line readout mode). To set the readout row, it is necessary to input an external signal to the specified terminals (ADR, Enadr). For details, see "Timing chart for multi-line readout mode".

■ Readout example of multi-line readout mode

(a) Selected rows 10 to 17, 50 to 54, 100 to 101, and 200 to 202 rows (total 18 rows)



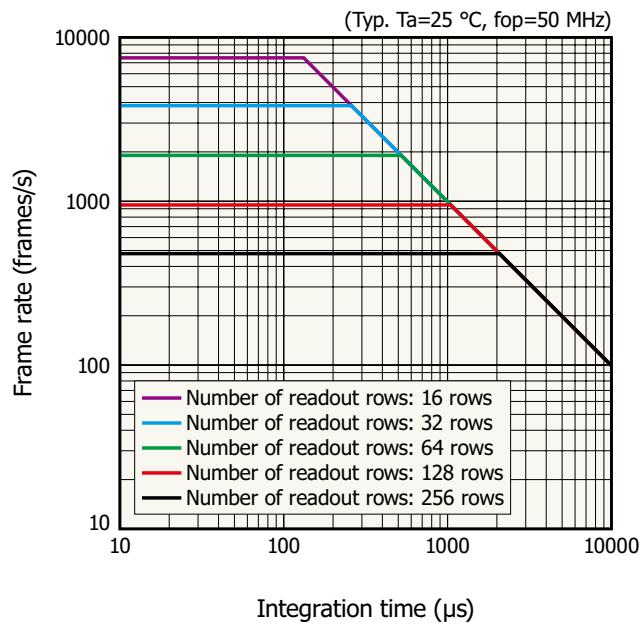
(b) Selected rows 7 to 106, 151 to 160, and 201 to 250 rows (total 160 rows)



: readout region

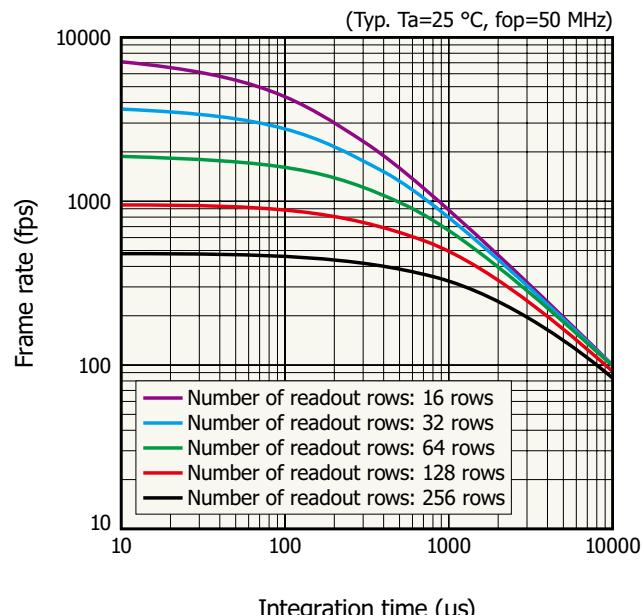
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■ Multi-line readout mode_frame rate in IWR operation



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■ Multi-line readout mode_frame rate in ITR operation



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■ Recommended drive conditions (Ta=25 °C)

Parameter		Symbol	Min.	Typ.	Max.	Unit
Supply voltage	Vdd1	4.9	5.0	5.1	V	
	Vdd2	3.2	3.3	3.4	V	
Supply current	Ivdd1	-	63	120	mA	
	Ivdd2	-	30	60	mA	
First-stage amplifier reference voltage*18	Supply voltage	Vinp	3.0	3.1	3.2	V
	Supply current	Ivinp	-	-	10	mA
Video line reset voltage	Supply voltage	Vrst	1.6	1.7	1.8	V
	Supply current	Ivrst	-	-	10	mA
Element bias voltage*18	Supply voltage	Vpdn	3.08	Vinp + 0.08	3.28	V
	Supply current	Ivpdn	-	-	20	mA
Pixel bias voltage*19	Supply voltage	Vb1	2.5	3.5	4.5	V
	Supply current	Ivb1	-	-	10	mA
MCLK voltage	High	Vi(MCLK)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
MST voltage	High	Vi(MST)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
SHP voltage	High	Vi(SHP)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
Reset voltage	High	Vi(Reset)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
ENadr voltage	High	Vi(ENadr)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
ADR voltage	High	Vi(ADR)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
Mode1 voltage*20	High	Vi(Mode1)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
Mode2 voltage*21	High	Vi(Mode2)	Vdd2 - 0.25	Vdd2	Vdd2 + 0.25	V
	Low		-	-	0.25	
Video output voltage	Dark output	Vs(dark)	2.2	2.4	2.6	V
	Saturation output	Vs(sat)	0.1	0.3	0.5	
Output impedance	Zo	-	-	1	-	kΩ
Clock frequency	fop	-	-	-	50	MHz
Data rate	DR	-	-	fop/4	-	Hz
Frame rate (fop=50 MHz)*22	FR	-	-	-	503	fps

*18: Set Vpdn to a higher voltage than Vinp.

*19: Setting values vary depending on the sample. For the setting value, refer to the Vb1 value written on the final inspection sheet enclosed at the time of shipment.

*20: Set to 3.3 V.

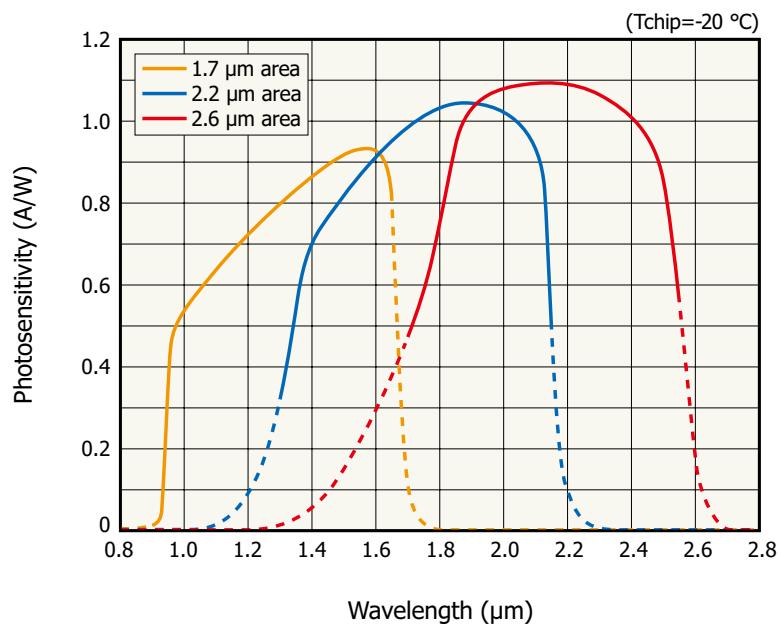
*21: High (3.3 V): All-line readout mode, Low (0 V): Multi-line readout mode

*22: All-line readout mode, integration time=1.98 ms, in IWR operation

■ Operation mode selection

Terminal name	Pin no.	Input	Description
Mode1	17	High=3.3 V [Vdd2(3.3 V)]	Apply the fixed voltage indicated on the left.
Mode2	25	High=3.3 V [Vdd2(3.3 V)]	All-line readout mode
		Low=0 V (GND)	Multi-line readout mode

■ Spectral response



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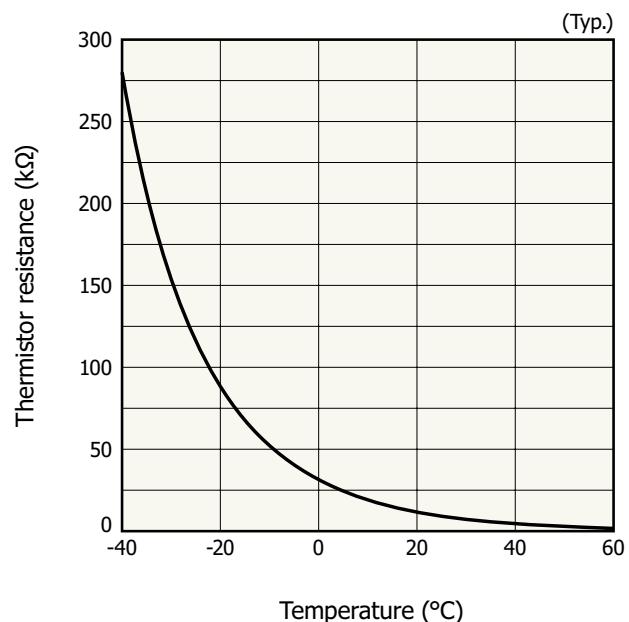
■ Specifications of built-in TE-cooler/thermistor (Ta=25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Recommended TE-cooler operating current	ITE		-	-	2.8	A
Recommended TE-cooler operating voltage	VTE		-	-	6.2	V
Temperature difference* ²³	ΔT	ITE=2.8 A, Ta=25 °C	50	-	-	°C
Thermistor resistance	R _{th}	T _{chip} =25 °C	9	10	11	kΩ
Thermistor B constant	B	* ²⁴	-	3660	-	K

*23: Temperature difference between the photosensitive area and package heat dissipation area

*24: T₁=25 °C, T₂=-20 °C

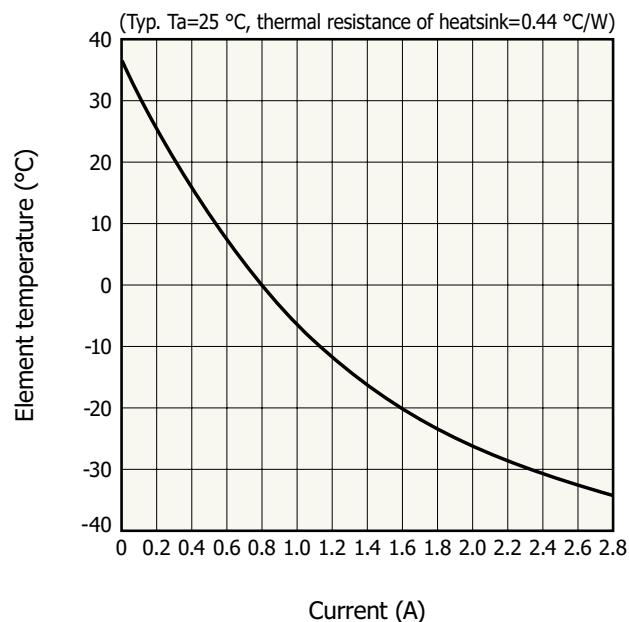
Thermistor temperature characteristics



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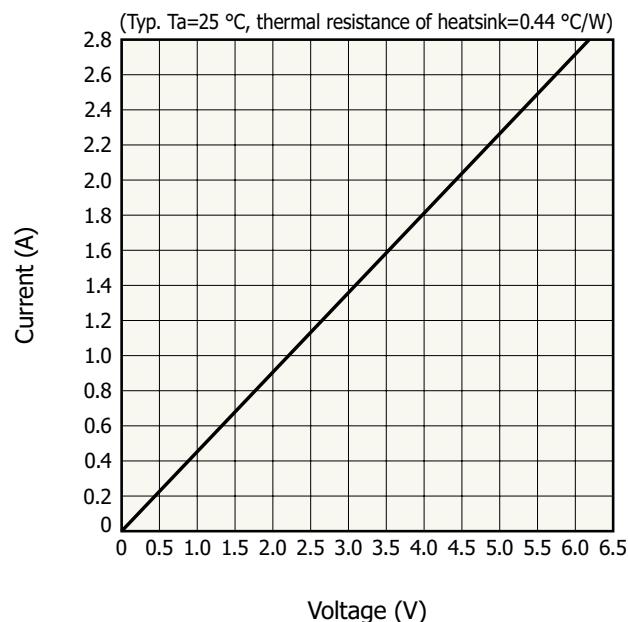
Temperature ($^{\circ}\text{C}$)	Thermistor resistance ($k\Omega$)	Temperature ($^{\circ}\text{C}$)	Thermistor resistance ($k\Omega$)
-40	281	20	12.5
-35	208	25	10
-30	155	30	8.06
-25	117	35	6.53
-20	88.8	40	5.32
-15	68.4	45	4.36
-10	53	50	3.59
-5	41.2	55	2.97
0	32.1	60	2.47
5	25.1	65	2.07
10	19.8	70	1.74
15	15.7		

Cooling characteristics of TE-cooler



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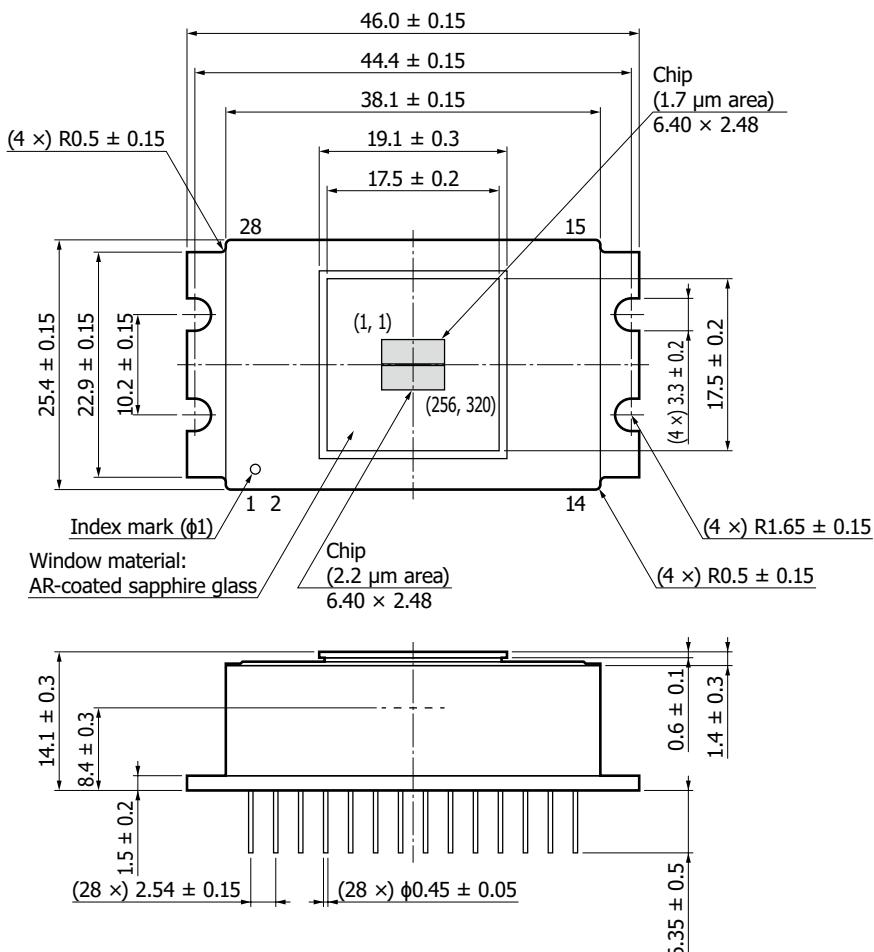
Current vs. voltage characteristics of TE-cooler



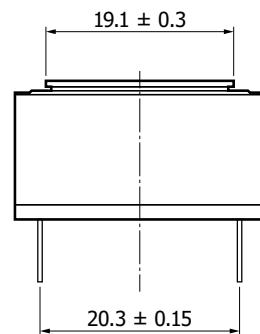
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 Dimensional outline (unit: mm)

G17242-0808T

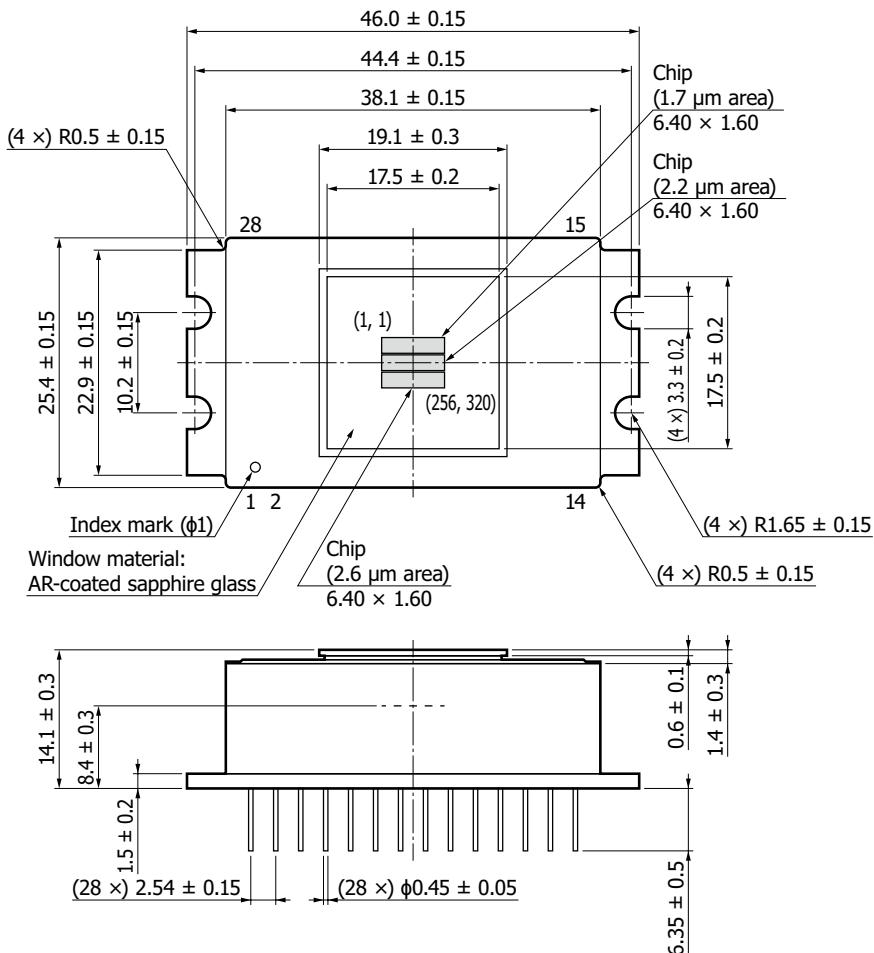


Pin No.	Symbol	Pin No.	Symbol
1	TE+	15	Vdd1
2	GND	16	Vdd2
3	Vpdn	17	Mode1
4	Vb1	18	VSP
5	Vinp	19	ADR
6	Vrst	20	SHP
7	Video1	21	MST
8	NC	22	MCLK
9	Video2	23	Reset
10	NC	24	ENadr
11	Video3	25	Mode2
12	NC	26	THERM1
13	Video4	27	THERM2
14	NC	28	TE-



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Pin No.	Symbol	Pin No.	Symbol
1	TE+	15	Vdd1
2	GND	16	Vdd2
3	Vpdn	17	Mode1
4	Vb1	18	VSP
5	Vinp	19	ADR
6	Vrst	20	SHP
7	Video1	21	MST
8	NC	22	MCLK
9	Video2	23	Reset
10	NC	24	ENadr
11	Video3	25	Mode2
12	NC	26	THERM1
13	Video4	27	THERM2
14	NC	28	TE-

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Pin connections

Pin no.	Symbol	Input/output	Description	Note
1	TE+	Input	TE-cooler (+)	-
2	GND	Input	0 V ground	0 V
3	Vpdn	Input	Photodiode bias voltage	3.18 V Typ.
4	Vb1	Input	Pixel bias voltage	2.5 V to 4.5 V
5	Vinp	Input	Charge amplifier reset voltage	3.1 V Typ.
6	Vrst	Input	Video line reset voltage	1.7 V Typ.
7	Video1	Output	Video output after integration (port 1)	0.1 V to 2.6 V
8	NC	-	-	-
9	Video2	Output	Video output after integration (port 2)	0.1 V to 2.6 V
10	NC	-	-	-
11	Video3	Output	Video output after integration (port 3)	0.1 V to 2.6 V
12	NC	-	-	-
13	Video4	Output	Video output after integration (port 4)	0.1 V to 2.6 V
14	NC	-	-	-
15	Vdd1	Input	+5 V power supply	+5 V
16	Vdd2	Input	+3.3 V power supply	+3.3 V
17	Mode1	Input	Mode switching signal	Set to High (3.3 V)
18	VSP	Output	Synchronization signal for multi-line readout mode	-
19	ADR	Input	Control pulse for multi-line readout mode	-
20	SHP	Input	Sample hold pulse	-
21	MST	Input	Frame scan start pulse	-
22	MCLK	Input	Control pulse for multi-line readout mode	-
23	Reset	Input	Charge amplifier reset pulse	-
24	ENadr	Input	Control pulse for multi-line readout mode	-
25	Mode2	Input	Mode switching signal	High (3.3 V): All-line readout mode Low (0 V): Multi-line readout mode
26	THERM1	Output	Thermistor	-
27	THERM2	Output	Thermistor	-
28	TE-	Input	TE-cooler (-)	-

Precautions

(1) Electrostatic countermeasures

This device has a built-in protection circuit against static electrical charges. However, to prevent destroying the device with electrostatic charges, take countermeasures such as grounding yourself, the workbench, and tools to prevent static discharges. Also protect this device from surge voltages which might be caused by peripheral equipment.

(2) Input window

If there is dust or stain on the input window, it will show up as black blemishes on the image. When cleaning, avoid rubbing the window surface with dry cloth, dry cotton swab or the like, since doing so may generate static electricity. Use soft cloth, paper or a cotton swab, or the like moistened with alcohol to wipe off dust and stain. Then blow compressed air so that no stain remains.

(3) Soldering

To prevent damaging the device during soldering, take precautions to prevent excessive soldering temperatures and times. Soldering should be performed within 10 seconds at a soldering temperature below 260 °C.

(4) Operating and storage environments

Handle the device within the temperature range specified in the absolute maximum ratings. Operating or storing the device at an excessively high temperature and humidity may cause variations in performance characteristics and must be avoided.

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

■ Precautions

- Disclaimer
- Safety consideration / Opto-semiconductor products
- Precautions / Image sensors

■ Catalog

- Selection guide / InGaAs image sensors
- Technical note / InGaAs area image sensors

The content of this document is current as of March 2025.

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